

Special Issue

Trends in Flexible Sensor Technology for Personal, Industrial, and Structural Applications

Message from the Guest Editors

Flexible sensor technology is at the forefront of innovation, enabling new capabilities across personal health, industrial monitoring, and structural applications. This Special Issue aims to highlight the latest developments in this evolving field. Current research can be broadly categorized into three key areas: Advanced materials; Circuits and signal processing for sensing interfaces; Emerging applications. This *Technologies* Special Issue invites high-quality submissions that address the latest trends, challenges, and breakthroughs in flexible sensor research. We welcome original research articles and reviews that contribute to the development and integration of flexible sensing technologies.

Guest Editors

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Deadline for manuscript submissions

30 May 2026



Technologies

an Open Access Journal
by MDPI

Impact Factor 3.6
CiteScore 8.5



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About the Journal

Message from the Editor-in-Chief

Technologies, provides a single focus for reporting on developments of all technologies, regardless of their application. It is our intention that *Technologies* becomes the journal of choice for both researchers wanting to publish their work and technologists wishing to exploit the high quality research across a wide range of potential applications. Through its open access policy, its quick publication cycle, *Technologies* will facilitate the rapid uptake and development of the research presented, ultimately providing benefit to the wider society.

Editor-in-Chief

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